

The NFI invites market parties to register their interest via TenderNed if they are able to supply a reballing machine that meets the specifications below. Or if you can provide a reasonable alternative or substitute.

Please express your interest within [20 days starting from the day of the TED publication] if you are interested.

The Procurement Execution Center (IUC) DJI will then contact you on behalf of the NFI.

Specifications

Supplier:

- The supplier (via a third party) has a service organization with coverage in the Netherlands.
- The supplier is located in a country that is a member of the Government Procurement Agreement (GPA).

Budget:

- The allocated budget is approximately €399,000,- including VAT including accessories.
- The maintenance budget for a preventive maintenance contract is maximum €18,975 including VAT/ year.

Requirements:

- The setup complies with (NEN-EN 50160 or equivalent and is suitable for use with the Dutch electricity grid of 230-240 volts and an alternating current with a frequency of 50Hz;
- Indication of setup/machine dimensions (LxWxH mm): 1500 x 1000 x 2000;
- The setup can both place and remove solder balls (both individually and in bulk);
- The setup can perform flux-free soldering using laser technology without requiring special tools;
- Additional reflow should not be necessary;
- The setup is suitable for solder ball diameters ranging from at least 60µm to 750µm;
- The ball placement speed must be accurate with a minimum of 5 balls per second. Additionally, repeatability up to 5 µm is also possible;
- The setup has high flexibility for the use of various solder alloys such as: Eutectic SnPb, High-lead SnPb, Lead-free SnAg, SnAgCu, AuSn, InSn, SnBi, etc.;
- The setup has high throughput speed and high accuracy of the (X,Y,Z) axis system;
- The setup has the ability for automated fiducial alignment;
- The setup has the ability for post-processing and repair of e.g., one solder ball using deballing and reballing (removing/placing one or more solder balls);

- The setup allows for quality control of solder ball placement using a camera;

The setup is quickly and easily adjustable/configurable for placing a different diameter solder ball. Any necessary accessories for this should also be provided.